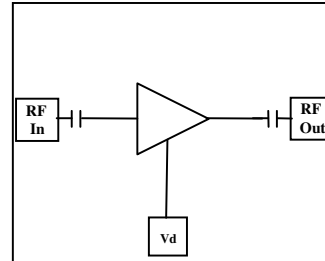


## 2 – 6 GHz 20dBm Medium Power Amplifier

### Features

- ◆ Frequency Range : 2 – 6GHz
- ◆ 20 dBm output P1dB
- ◆ 11 dB Power gain
- ◆ 28% PAE
- ◆ High IP3
- ◆ Input Return Loss > 14dB
- ◆ Output Return Loss > 14dB
- ◆ Self bias operation
- ◆ No external matching required
- ◆ DC decoupled input and output
- ◆ 0.15  $\mu\text{m}$  InGaAs pHEMT Technology
- ◆ Chip dimension: 2.5 x 0.8 x 0.1 mm

### Functional Diagram



### Typical Applications

- ◆ RADAR
- ◆ Military & space
- ◆ LMDS, VSAT

### Description

The AMT2122084 is a 2-6GHz medium power amplifier with 20dBm power output. The MPA operates in 2 – 6GHz frequency range and features 11dB of gain with input and output return losses of 14dB respectively. The MPA has a high IP3 of 30dBm and 28% PAE. This feature enables it to be used in the applications requiring efficiency along with linearity. The chip operates with single bias supply voltage. The die is fabricated using a reliable 0.15 $\mu\text{m}$  InGaAs pHEMT technology. The Circuit grounds are provided through vias to the backside metallization.

### Absolute Maximum Ratings <sup>(1)</sup>

Parameter	Absolute Maximum	Units
Drain bias voltage (Vd)	+6	volts
Drain current (Id)	140	mA
RF input power (RFIn at Vd=9V)	21	dBm
Operating temperature	-50 to +85	°C
Storage Temperature	-65 to +150	°C

1. Operation beyond these limits may cause permanent damage to the component

**Electrical Specifications <sup>(1)</sup> @ T<sub>A</sub> = 25 °C, V<sub>d</sub> = 4V, Z<sub>o</sub> =50 Ω**

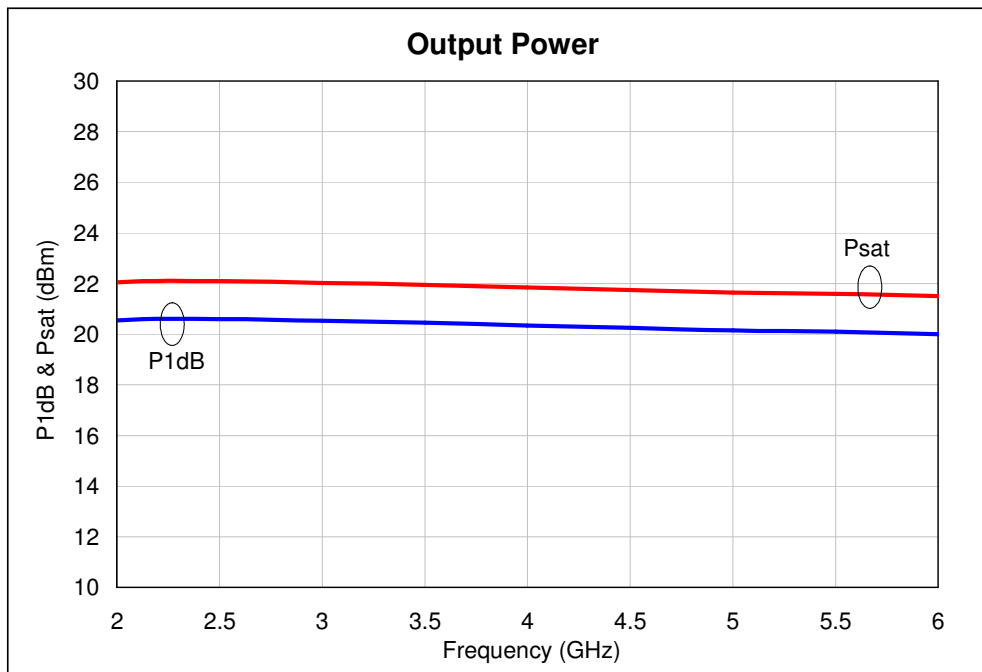
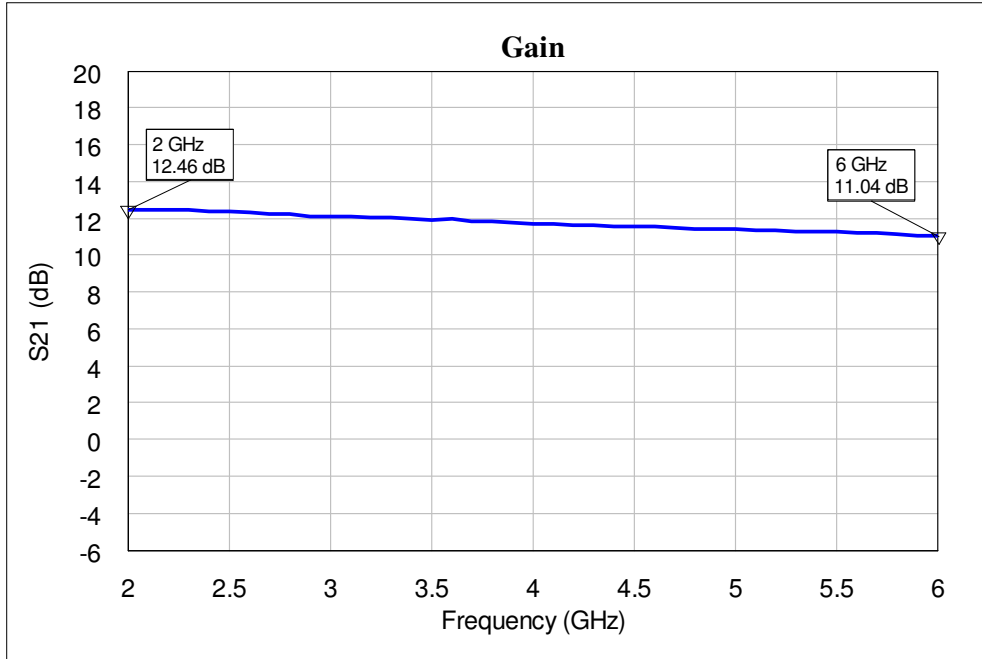
Parameter	Typ.	Units
Frequency Range	2 – 6	GHz
Gain	11	dB
Gain Flatness	+/-0.7	dB
Output Power (P1 dB)	20	dBm
Input Return Loss	14	dB
Output Return Loss	14	dB
Saturated output power (Psat)	21	dBm
Output Third Order Intercept (IP3)	30	dBm
Power Added Efficiency (PAE)	28%	--
Supply Current	88	mA

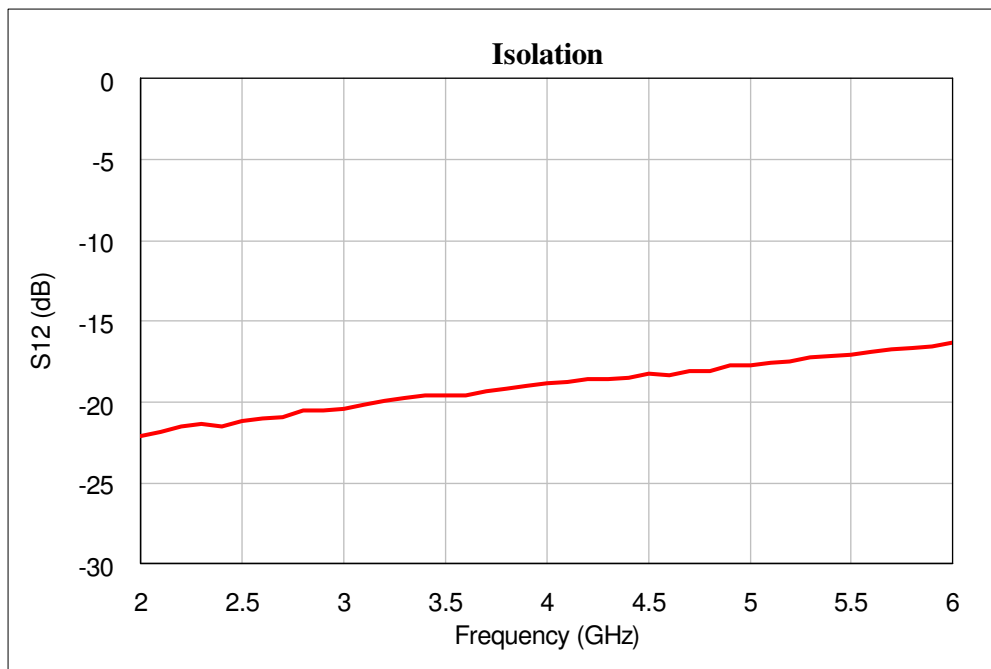
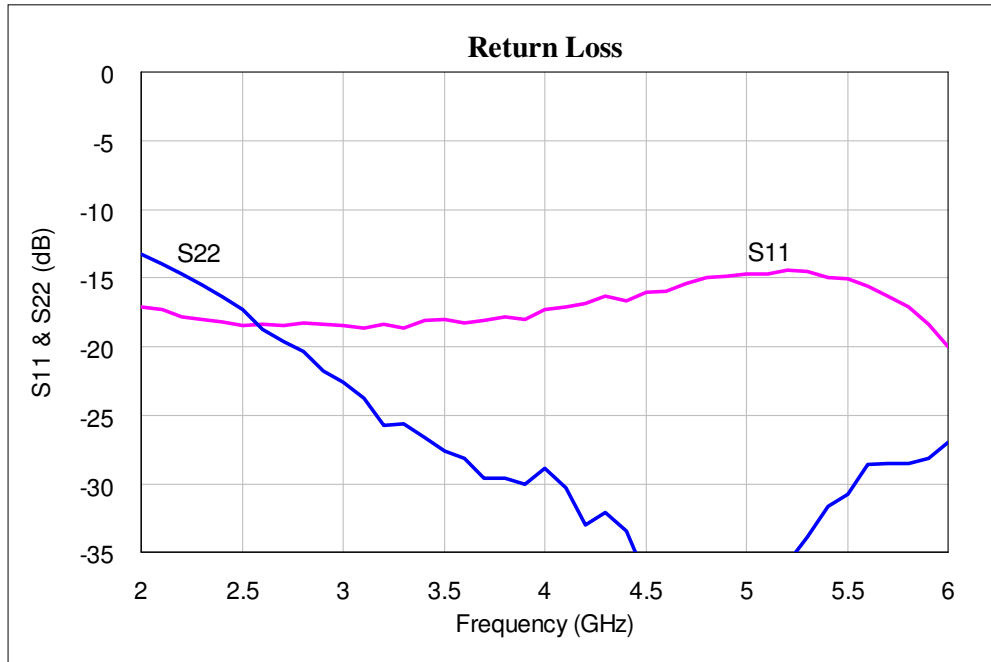
**Note:**

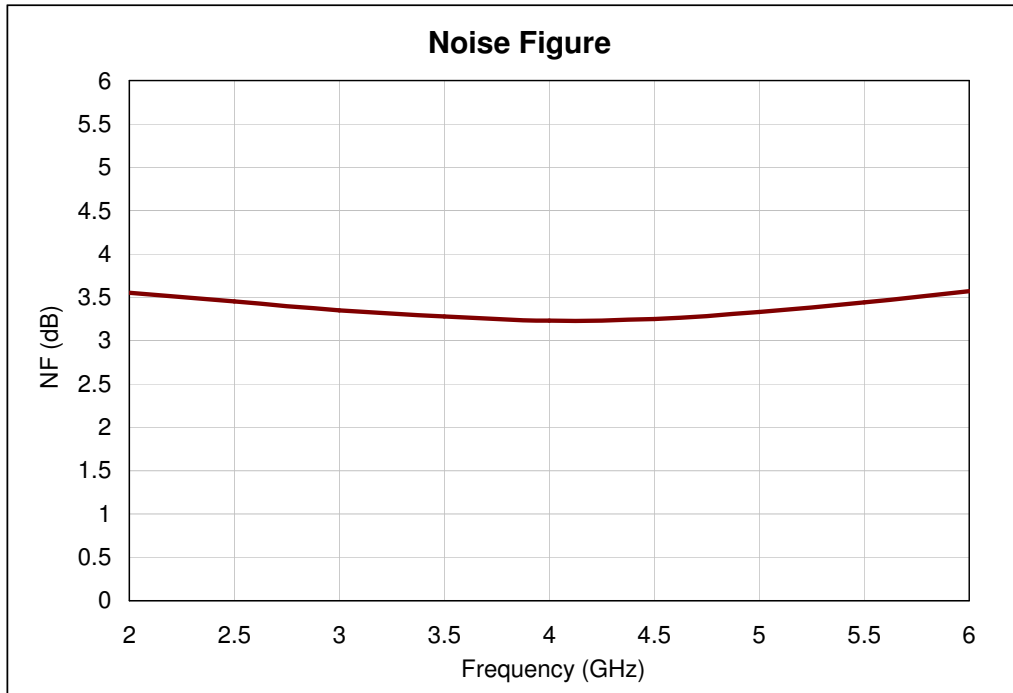
1. Electrical specifications as measured in test fixture.

**Test fixture data**

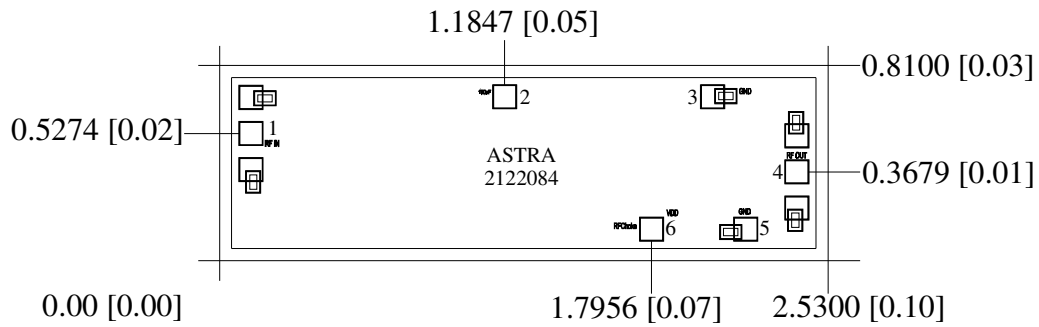
$V_d = 4V$ , Total Current = 88mA,  $T_A = 25^\circ C$



**Test fixture data**
 $V_d = 4V, \text{ Total Current} = 88mA, T_A = 25^\circ C$ 


**Test fixture data** $V_d = 4V$ , Total Current = 88mA,  $T_A = 25^\circ C$ 

## Bond Pad Locations

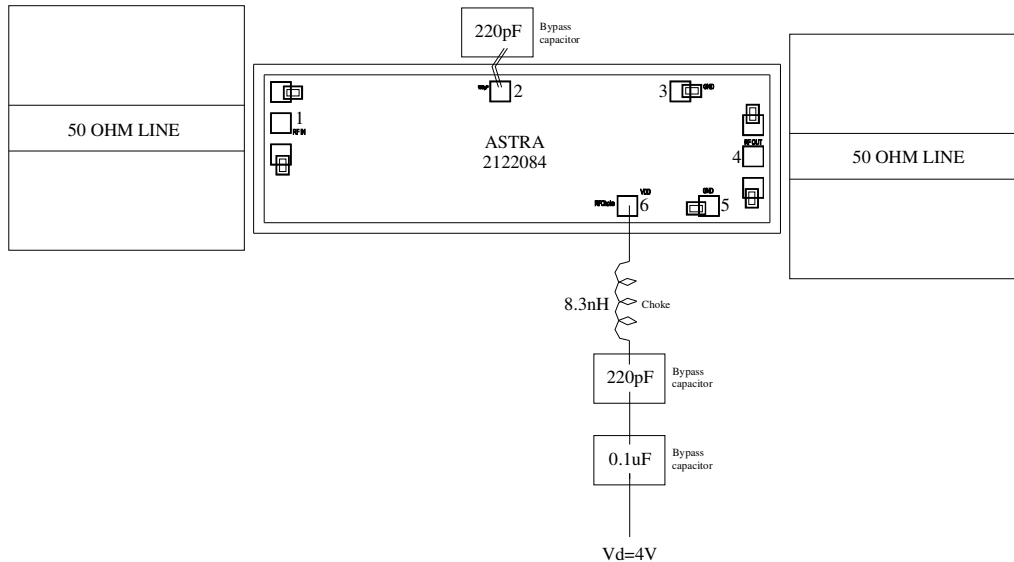


**Units:** millimeters

**Note:**

1. All RF and DC bond pads are 100 $\mu$ m x 100 $\mu$ m
2. Pad no. 1 : RF IN
3. Pad no. 2 : Source bypass capacitor (220pF)
4. Pad no. 4 : RF Output
5. Pad no. 6 : Drain Voltage (Vd)

## Recommended Assembly Diagram


**Note:**

1. Two 1 mil (0.0254mm) bond wires of minimum length should be used for RF input and output.
2. Two 1 mil (0.0254mm) bond wires of minimum length should be used from chip bond pad to 100pF capacitor.
3. Input and output 50 ohm lines are on 5 mil RT Duroid substrate
4. 0.1  $\mu$ F capacitors may be additionally used as a second level of bypass for reliable operation
5. The RF input & output ports are DC decoupled on-chip.
6. Proper heat sink like Copper tungsten or copper molybdenum to be used for better reliability of chip

**Die attach:** For Epoxy attachment, use of a two-component conductive epoxy is recommended. An epoxy fillet should be visible around the total die periphery. If Eutectic attachment is preferred, use of fluxless AuSn (80/20) 1-2 mil thick preform solder is recommended. Use of AuGe preform should be strictly avoided.

**Wire bonding:** For DC pad connections use either ball or wedge bonds. For best RF performance, use of 150 - 200 $\mu$ m length of wedge bonds is advised. Single Ball bonds of 250-300 $\mu$ m though acceptable, may cause a deviation in RF performance.



**GaAs MMIC devices are susceptible to Electrostatic discharge. Proper precautions should be observed during handling, assembly & testing**

All information and Specifications are subject to change without prior notice

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